

1.38 W/mK

5316 is a room temperature curing, black, flowable, electrically isolating, thermally conductive epoxy. The material was designed specifically for underfilling, staking and encapsulating electronics on circuit boards as well as potting and encapsulating power supplies, transformers, and coils. 5316 features a long work life and is ideal for applications requiring a self-leveling, thermal conductive epoxy with resistance to solvents and chemicals. 5316 is supplied as a two-part room temperature storage kit. Contact customer service for pre-mixed and frozen options.

UNCURED	
Pot Life @ 25°C	1.5 hours
Viscosity, Mixed @ 25°C	12,500 cPs
Viscosity, Part A @ 25°C	Paste
Viscosity, Part B @ 25°C	250 cPs
Shelf Life @ 25°C	12 Months
Mix Ratio	100A:5.6B Parts By Weight
CURE OPTIONS	24 hours @ 25°C 4 hours @ 65°C
CURED PROPERTIES	Based on cure of 24 hours @ 25°C
Color	Black
Shore D Hardness	85
Glass Transition Temp (°C)	55
Density (g/cc)	2.5
Lap Shear 2024T3 Clad (psi)	2,500
Volume Resistivity (ohm-cm)	2.25 E +15
THERMAL PROPERTIES	Based on cure of 24 hours @ 25°C
Glass Transition Temp (°C)	55
Degradation Temp. (°C)	300
Thermal Conductivity (W/mK)	1.38
OUTGASSING PROPERTIES	Based on cure of 4 hours @ 65°C
TML(%)	0.44
CVCM(%)	0.01
WVR(%)	0.07
OUTGASSING PROPERTIES	Based on cure of 24 hours @ 25°C

KEY FEATURES

Electrically Isolating

High Thermal Conductivity

Low Shrinkage

Flowable

Talk to an engineer:

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Rev C

8-27-2020

TML(%)	0.41
CVCM(%)	0.01
WVR(%)	0.07